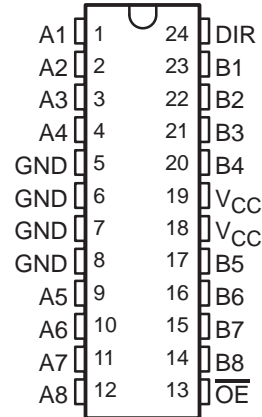


- **3-State Outputs Drive Bus Lines Directly**
- **Flow-Through Architecture Optimizes PCB Layout**
- **Center-Pin  $V_{CC}$  and GND Configurations Minimize High-Speed Switching Noise**
- **EPIC™ (Enhanced-Performance Implanted CMOS) 1- $\mu$ m Process**
- **500-mA Typical Latch-Up Immunity at 125°C**
- **Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages, and Standard Plastic 300-mil DIPs (NT)**

DB, DW, NT, OR PW PACKAGE  
(TOP VIEW)



**description**

This octal bus transceiver is designed for asynchronous two-way communication between data buses. The control-function implementation minimizes external timing requirements.

The device allows noninverted data transmission from the A bus to the B bus or from the B bus to the A bus, depending on the logic level at the direction-control (DIR) input. The output-enable ( $\overline{OE}$ ) input can be used to disable the device so that the buses are effectively isolated.

The 74AC11245 is characterized for operation from  $-40^{\circ}\text{C}$  to  $85^{\circ}\text{C}$ .

FUNCTION TABLE

OUTPUT ENABLE $\overline{OE}$	DIRECTION CONTROL DIR	OPERATION
L	L	B data to A bus
L	H	A data to B bus
H	X	Isolation



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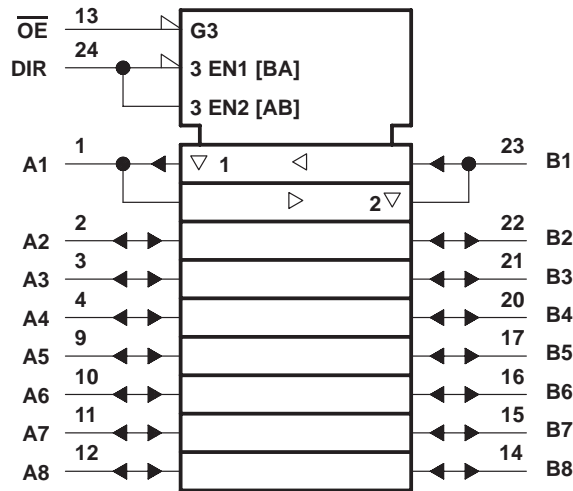
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**74AC11245**  
**OCTAL BUS TRANSCEIVER**  
**WITH 3-STATE OUTPUTS**

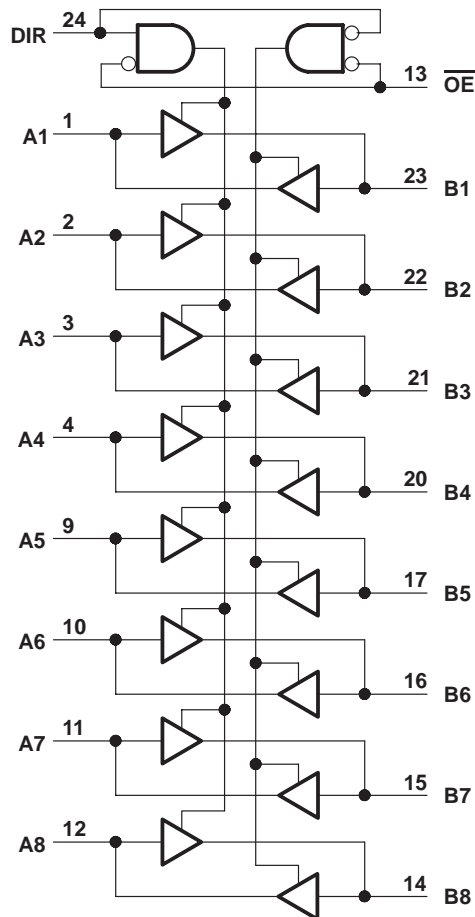
SCAS010B – JULY 1987 – REVISED APRIL 1996

**logic symbol†**



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

**logic diagram (positive logic)**



**absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†**

Supply voltage range, $V_{CC}$ .....	–0.5 V to 7 V	
Input voltage range, $V_I$ (see Note 1) .....	–0.5 V to $V_{CC} + 0.5$ V	
Output voltage range, $V_O$ (see Note 1) .....	–0.5 V to $V_{CC} + 0.5$ V	
Input clamp current, $I_{IK}$ ( $V_I < 0$ or $V_I > V_{CC}$ ) .....	±20 mA	
Output clamp current, $I_{OK}$ ( $V_O < 0$ or $V_O > V_{CC}$ ) .....	±50 mA	
Continuous output current, $I_O$ ( $V_O = 0$ to $V_{CC}$ ) .....	±50 mA	
Continuous current through $V_{CC}$ or GND .....	±200 mA	
Maximum power dissipation at $T_A = 55^\circ\text{C}$ (in still air) (see Note 2):	DB package .....	0.65 W
	DW package .....	1.7 W
	NT package .....	1.3 W
	PW package .....	0.7 W
Storage temperature range, $T_{stg}$ .....	–65°C to 150°C	

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.  
 2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils, except for the NT package, which has a trace length of zero.

**recommended operating conditions**

		MIN	NOM	MAX	UNIT
$V_{CC}$	Supply voltage	3	5	5.5	V
$V_{IH}$	High-level input voltage	$V_{CC} = 3$ V	2.1		V
		$V_{CC} = 4.5$ V	3.15		
		$V_{CC} = 5.5$ V	3.85		
$V_{IL}$	Low-level input voltage	$V_{CC} = 3$ V		0.9	V
		$V_{CC} = 4.5$ V		1.35	
		$V_{CC} = 5.5$ V		1.65	
$V_I$	Input voltage	0		$V_{CC}$	V
$V_O$	Output voltage	0		$V_{CC}$	V
$I_{OH}$	High-level output current	$V_{CC} = 3$ V		–4	mA
		$V_{CC} = 4.5$ V		–24	
		$V_{CC} = 5.5$ V		–24	
$I_{OL}$	Low-level output current	$V_{CC} = 3$ V		12	mA
		$V_{CC} = 4.5$ V		24	
		$V_{CC} = 5.5$ V		24	
$\Delta t/\Delta v$	Input transition rise or fall rate	0		10	ns/V
$T_A$	Operating free-air temperature	–40		85	°C

**74AC11245**  
**OCTAL BUS TRANSCEIVER**  
**WITH 3-STATE OUTPUTS**  
 SCAS010B – JULY 1987 – REVISED APRIL 1996

**electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)**

PARAMETER	TEST CONDITIONS	V <sub>CC</sub>	T <sub>A</sub> = 25°C			MIN	MAX	UNIT	
			MIN	TYP	MAX				
V <sub>OH</sub>	I <sub>OH</sub> = -50 μA	3 V	2.9			2.9		V	
		4.5 V	4.4			4.4			
		5.5 V	5.4			5.4			
	I <sub>OH</sub> = -4 mA	3 V	2.58			2.48			
		4.5 V	3.94			3.8			
		5.5 V	4.94			4.8			
I <sub>OH</sub> = -75 mA <sup>†</sup>	5.5 V				3.85				
V <sub>OL</sub>	I <sub>OL</sub> = 50 μA	3 V				0.1		V	
		4.5 V				0.1			
		5.5 V				0.1			
	I <sub>OL</sub> = 12 mA	3 V				0.36			
		4.5 V				0.36			
		5.5 V				0.36			
I <sub>OL</sub> = 24 mA	5.5 V				1.65				
I <sub>I</sub>	A or B ports <sup>‡</sup>	V <sub>O</sub> = V <sub>CC</sub> or GND	5.5 V				±0.5	±5	μA
	$\overline{\text{OE}}$ or DIR						±0.1	±1	
I <sub>CC</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND, I <sub>O</sub> = 0	5.5 V				8	80	μA	
C <sub>i</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND	5 V				4		pF	
C <sub>io</sub>	V <sub>O</sub> = V <sub>CC</sub> or GND	5 V				12		pF	

<sup>†</sup> Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.

<sup>‡</sup> For I/O ports, the parameter I<sub>OZ</sub> includes the input leakage current.

**switching characteristics over recommended operating free-air temperature range, V<sub>CC</sub> = 3.3 V ± 0.3 V (unless otherwise noted) (see Figure 1)**

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T <sub>A</sub> = 25°C			MIN	MAX	UNIT
			MIN	TYP	MAX			
t <sub>PLH</sub>	A or B	B or A	1.5	6.5	11.2	1.5	12.5	ns
t <sub>PHL</sub>			1.5	5.7	8.5	1.5	9.7	
t <sub>PZH</sub>	$\overline{\text{OE}}$	B or A	1.5	8.6	14.2	1.5	15.9	ns
t <sub>PZL</sub>			1.5	8.2	11.5	1.5	12.7	
t <sub>PHZ</sub>	$\overline{\text{OE}}$	B or A	1.5	7.7	10.5	1.5	11.3	ns
t <sub>PLZ</sub>			1.5	8.5	12	1.5	13	

**switching characteristics over recommended operating free-air temperature range, V<sub>CC</sub> = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)**

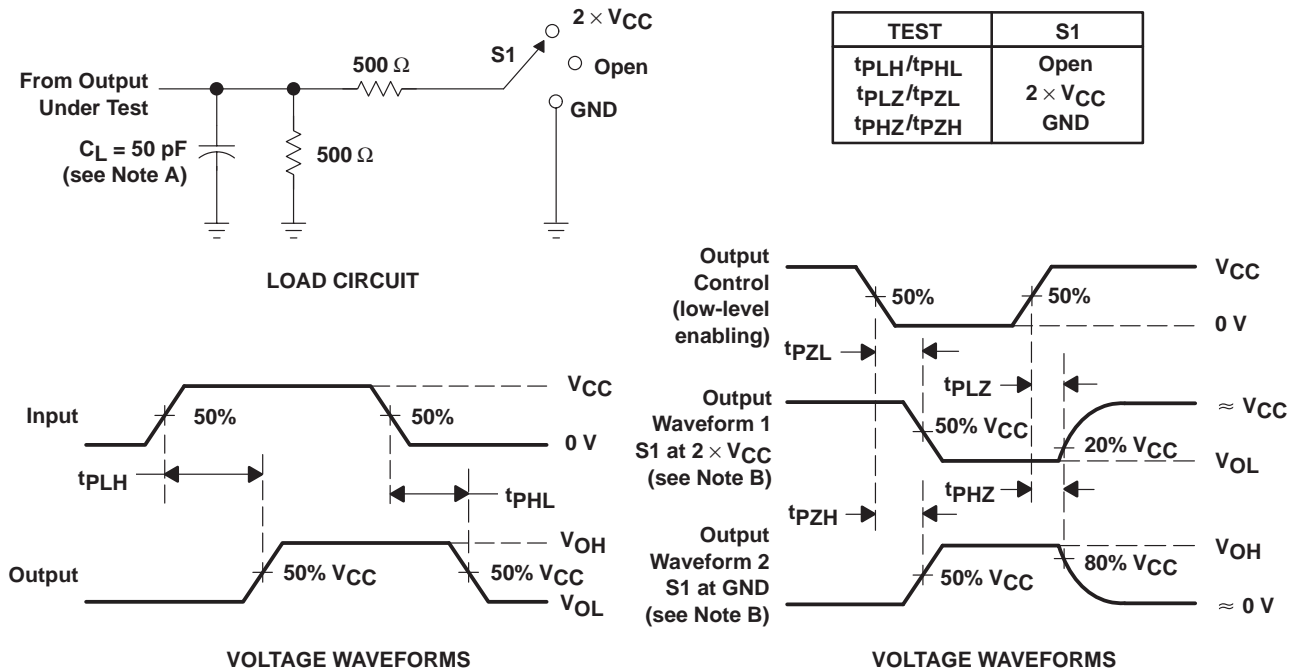
PARAMETER	FROM (INPUT)	TO (OUTPUT)	T <sub>A</sub> = 25°C			MIN	MAX	UNIT
			MIN	TYP	MAX			
t <sub>PLH</sub>	A or B	B or A	1.5	4.8	8.5	1.5	9.5	ns
t <sub>PHL</sub>			1.5	4.1	6.3	1.5	6.9	
t <sub>PZH</sub>	$\overline{\text{OE}}$	B or A	1.5	6.2	10.2	1.5	11.4	ns
t <sub>PZL</sub>			1.5	5.9	8.6	1.5	9.5	
t <sub>PHZ</sub>	$\overline{\text{OE}}$	B or A	1.5	6.4	8.8	1.5	9.5	ns
t <sub>PLZ</sub>			1.5	7	9.6	1.5	10.4	



operating characteristics,  $V_{CC} = 5\text{ V}$ ,  $T_A = 25^\circ\text{C}$

PARAMETER		TEST CONDITIONS	TYP	UNIT
$C_{pd}$	Power dissipation capacitance per transceiver	Outputs enabled	64	pF
		Outputs disabled		

**PARAMETER MEASUREMENT INFORMATION**



- NOTES: A.  $C_L$  includes probe and jig capacitance.  
 B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.  
 C. All input pulses are supplied by generators having the following characteristics:  $PRR \leq 1\text{ MHz}$ ,  $Z_O = 50\ \Omega$ ,  $t_r = 3\text{ ns}$ ,  $t_f = 3\text{ ns}$ .  
 D. The outputs are measured one at a time with one input transition per measurement.

**Figure 1. Load Circuit and Voltage Waveforms**

**PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
74AC11245DBLE	OBSOLETE	SSOP	DB	24		TBD	Call TI	Call TI
74AC11245DBR	OBSOLETE	SSOP	DB	24		TBD	Call TI	Call TI
74AC11245DW	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74AC11245DWE4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74AC11245DWG4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74AC11245DWR	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74AC11245DWRE4	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74AC11245DWRG4	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74AC11245NT	ACTIVE	PDIP	NT	24	15	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
74AC11245NTE4	ACTIVE	PDIP	NT	24	15	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
74AC11245PWLE	OBSOLETE	TSSOP	PW	24		TBD	Call TI	Call TI

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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**TAPE AND REEL INFORMATION**

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
74AC11245DWR	SOIC	DW	24	2000	330.0	24.4	10.75	15.7	2.7	12.0	24.0	Q1

**TAPE AND REEL BOX DIMENSIONS**



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
74AC11245DWR	SOIC	DW	24	2000	346.0	346.0	41.0



DB (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.  
 D. Falls within JEDEC MO-150

4040065 /E 12/01

PW (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



4040064/F 01/97

- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.  
 D. Falls within JEDEC MO-153

# MECHANICAL DATA

NT (R-PDIP-T\*\*) 24 PINS SHOWN

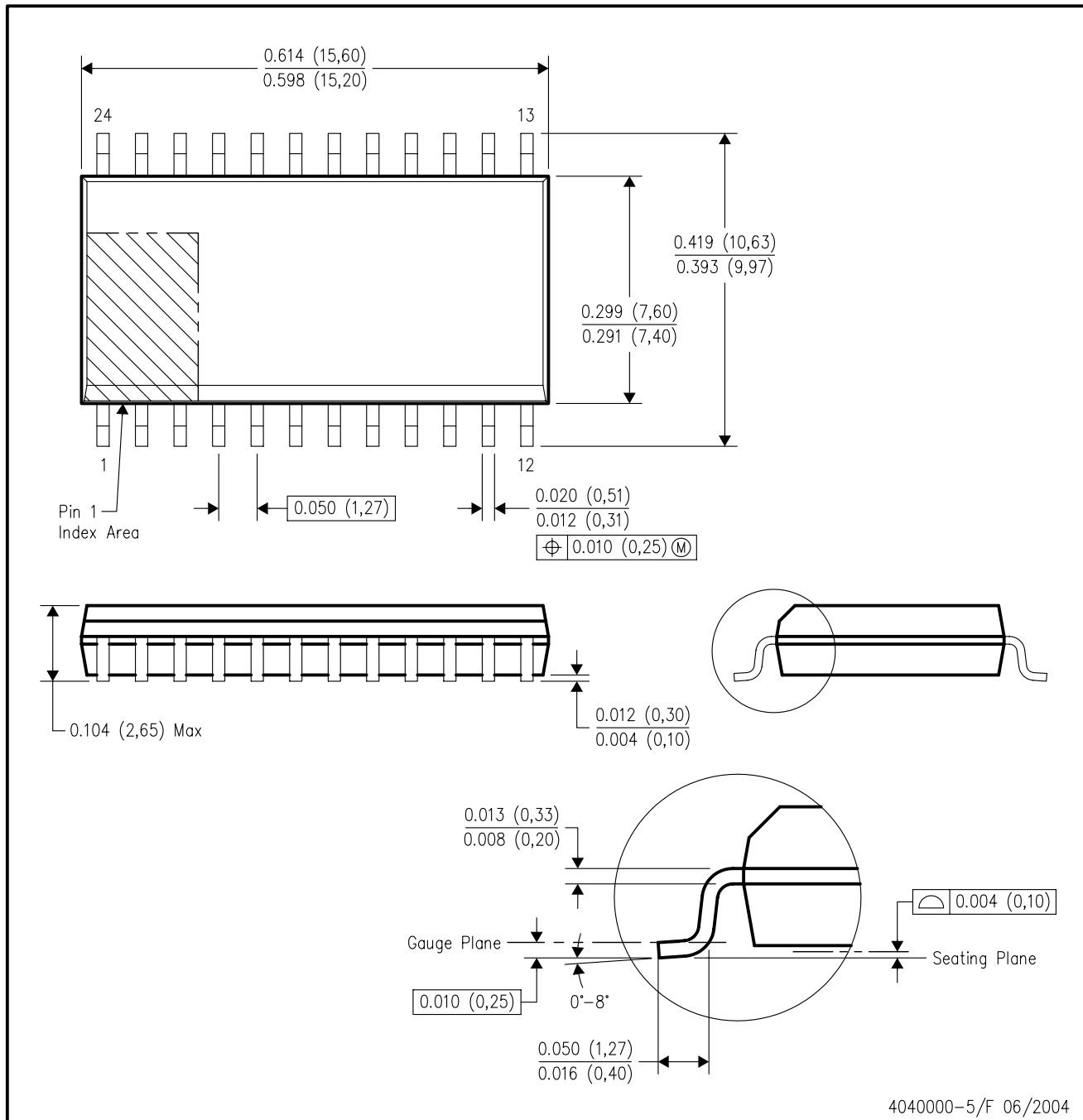
PLASTIC DUAL-IN-LINE PACKAGE



- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
  - B. This drawing is subject to change without notice.
  -  The 28 pin end lead shoulder width is a vendor option, either half or full width.

DW (R-PDSO-G24)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
  - D. Falls within JEDEC MS-013 variation AD.

**PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/ Ball Finish	MSL Peak Temp <sup>(3)</sup>	Samples (Requires Login)
74AC11245DBLE	OBSOLETE	SSOP	DB	24		TBD	Call TI	Call TI	
74AC11245DW	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
74AC11245DWE4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
74AC11245DWG4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
74AC11245DWR	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
74AC11245DWRE4	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
74AC11245DWRG4	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
74AC11245NT	ACTIVE	PDIP	NT	24	15	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
74AC11245NTE4	ACTIVE	PDIP	NT	24	15	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
74AC11245PWLE	OBSOLETE	TSSOP	PW	24		TBD	Call TI	Call TI	

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

**Important Information and Disclaimer:** The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

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**TAPE AND REEL INFORMATION**
**REEL DIMENSIONS**

**TAPE DIMENSIONS**


A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

**TAPE AND REEL INFORMATION**

\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
74AC11245DWR	SOIC	DW	24	2000	330.0	24.4	10.75	15.7	2.7	12.0	24.0	Q1

TAPE AND REEL BOX DIMENSIONS



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
74AC11245DWR	SOIC	DW	24	2000	367.0	367.0	45.0



# MECHANICAL DATA

NT (R-PDIP-T\*\*) 24 PINS SHOWN

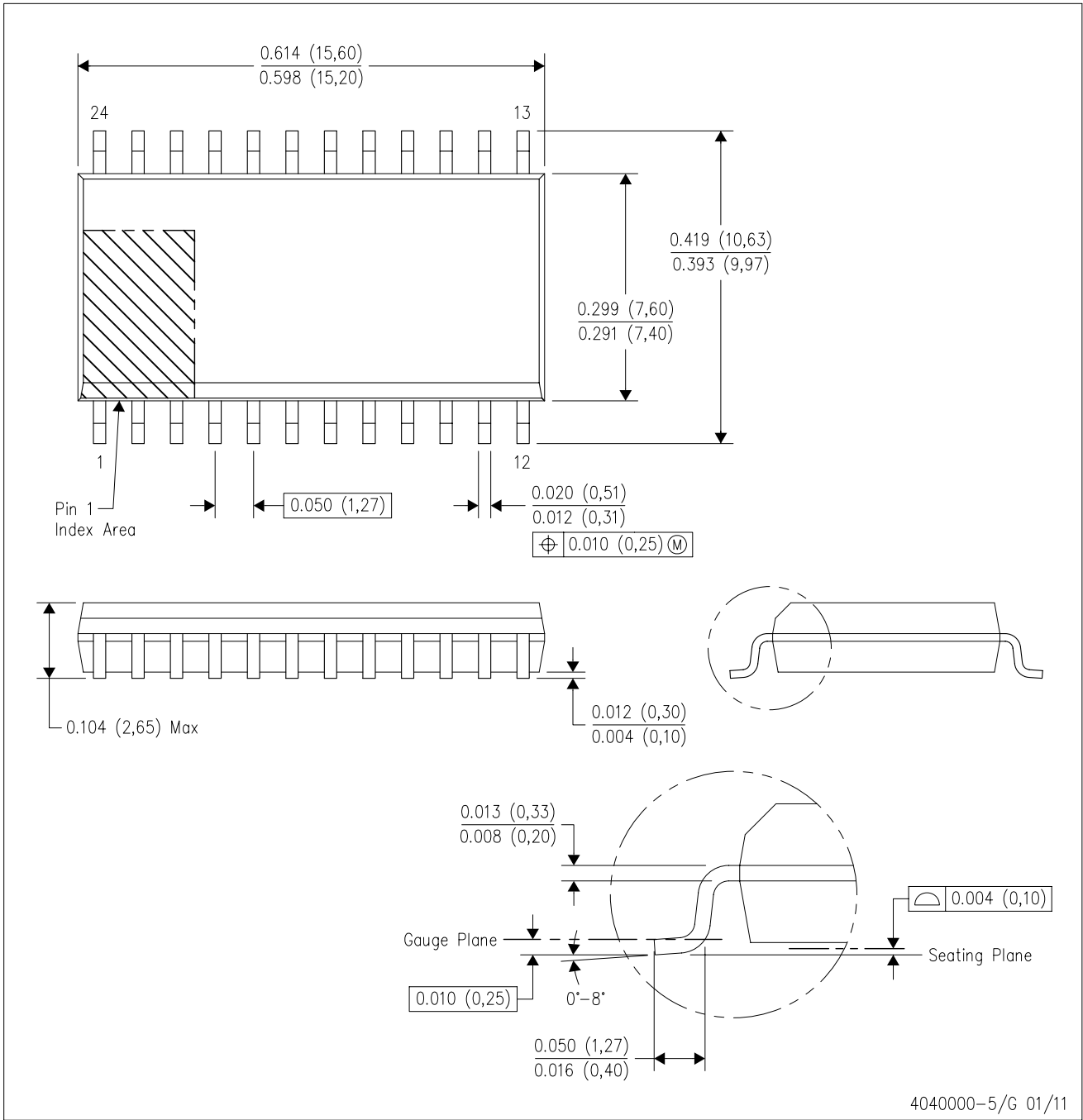
PLASTIC DUAL-IN-LINE PACKAGE



- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
  - B. This drawing is subject to change without notice.
  - $\triangle$  The 28 pin end lead shoulder width is a vendor option, either half or full width.

DW (R-PDSO-G24)

PLASTIC SMALL OUTLINE

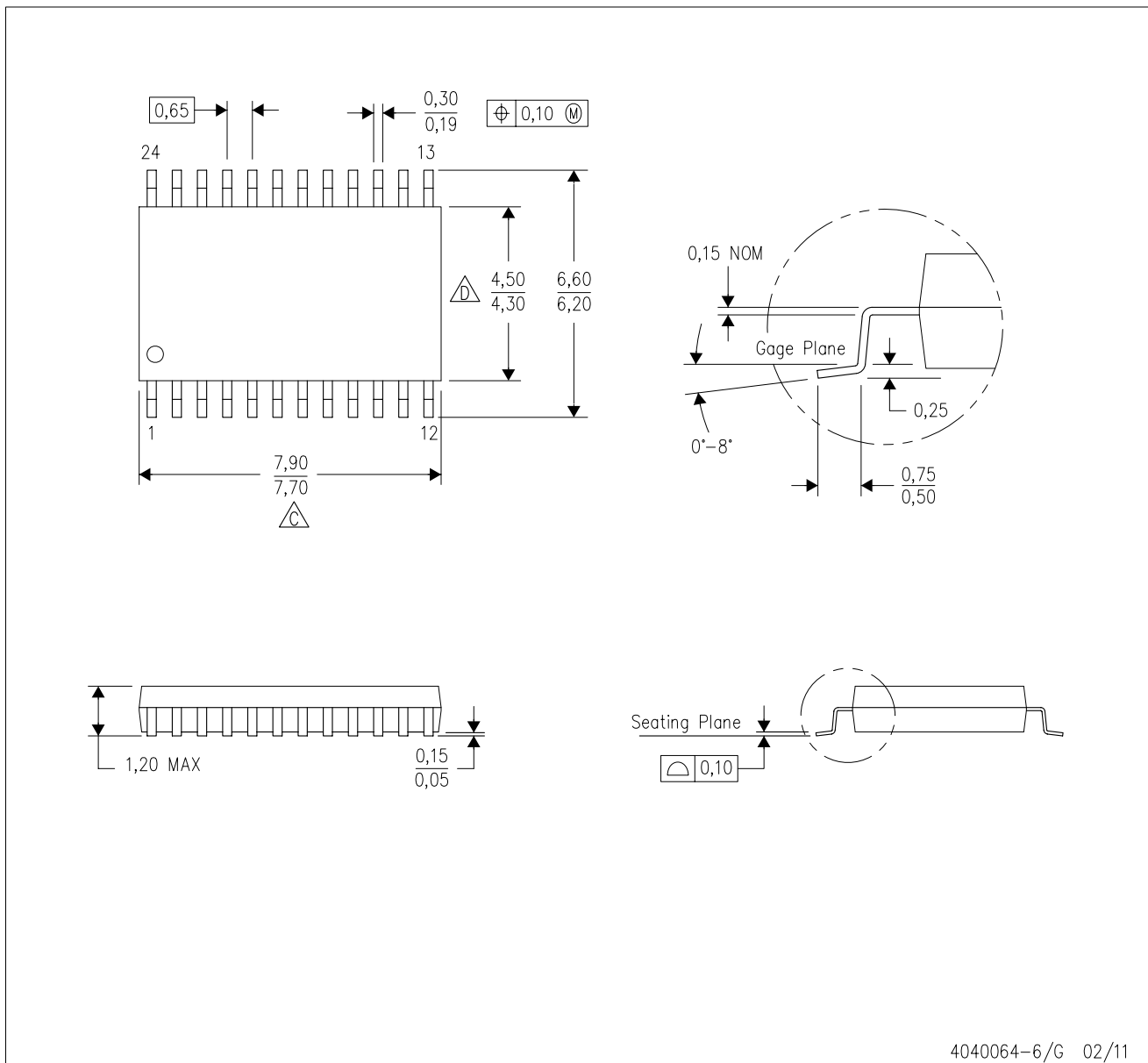


- NOTES:
- A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
  - D. Falls within JEDEC MS-013 variation AD.

# MECHANICAL DATA

PW (R-PDSO-G24)

PLASTIC SMALL OUTLINE



4040064-6/G 02/11

- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
  - B. This drawing is subject to change without notice.
  -  Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
  -  Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
  - E. Falls within JEDEC MO-153

DB (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.  
 D. Falls within JEDEC MO-150

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